#1722

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Warren M. Farnworth

Serial No.: 09/944,488

Filed: August 30, 2001

For: METHODS AND APPARATUS FOR STEREOLITHOGRAPHIC PROCESSING OF COMPONENTS AND ASSEMBLIES

Examiner: E. Luk

Group Art Unit: 1722

Attorney Docket No.: 2269-3996US
(99-0254.00/US)

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

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SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In compliance with the duty to disclose information material to patentability pursuant to 37 C.F.R. § 1.56, it is respectfully requested that this Supplemental Information Disclosure Statement be entered and the documents listed on attached Form PTO-1449 or PTO/SB/08 be considered by the Examiner and made of record. Copies of the listed documents are enclosed pursuant to 37 C.F.R. § 1.98(a).

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In accordance with 37 C.F.R. § 1.97(g) and (h), filing of this Supplemental Information Disclosure Statement is not to be construed as a representation that a search has been made or an admission that the information cited herein is, or is considered to be, material to patentability as defined in 37 C.F.R. § 1.56(b). Further, no representation is made by Applicant herein that no other possible material information as defined in 37 C.F.R. § 1.56 (b) exists.

U.S. Patent Documents

U.S. Patent No.	Publication Date	Patentee
6,251,488	06/26/01	Miller et al.
6,259,962	07/10/01	Gothait
6,268,584	07/31/01	Keicher et al.
6,326,698	12/04/01	Akram
6,337,122	01/08/02	Grigg et al.
6,391,251	05/21/02	Keicher et al.
6,432,752	08/13/02	Farnworth
6,489,007	12/03/02	Grigg et al.
6,506,671	01/14/03	Grigg
6,514,798	02/04/03	Farnworth
6,524,346	02/25/03	Farnworth
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6,544,465	04/08/03	Farnworth et al.
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6,544,902	04/08/03	Farnworth
6,548,897	04/15/03	Grigg
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6,569,753	05/27/03	Akram et al.
6,585,927	07/01/03	Grigg et al.
6,593,171	07/15/03	Farnworth
6,607,689	08/19/03	Farnworth
6,635,333	10/21/03	Grigg et al.

Other Documents

U.S. Patent Application Publication 2002/0066966 A1 to Farnworth, dated June 6, 2002

U.S. Patent Application Publication 2002/0098623 A1 to Akram, dated July 25, 2002

U.S. Patent Application Publication 2002/0105074 A1 to Akram et al., dated August 8, 2002

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U.S. Patent Application Publication 2003/0193092 A1 to Tan et al., dated October 16, 2003

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Webpage, Objet Prototyping the Future, "Objet FullCure700 Series", 1 page

Webpage, Objet Prototyping the Future, "How it Works", 2 pages

U.S. Patent Application No. 09/589,841, filed June 8, 2000, entitled "Stereolithographic Methods for Forming a Protective Layer on a Semiconductor Device Substrate and Substrates Including Protective Layers So Formed", inventor Farnworth et al.

U.S. Patent Application No. 09/590,646, filed June 8, 2000, entitled "Reinforced, Self-Aligning Conductive Structures for Semiconductor Device Components and Methods for Fabricating Same", inventor Williams et al.

U.S. Patent Application No. 09/651,930, filed August 31, 2000, entitled "Semiconductor Device Including Leads in Communication with Contact Pads Thereof and a Stereolithographically Fabricated Package Substantially Encapsulating the Leads and Methods for Fabricating the

Same", inventor Salman Akram

U.S. Patent Application No. 10/191,424, filed July 8, 2002, entitled "Semiconductor Devices with Permanent Polymer Stencil and Method for Manufacturing the Same", inventor Farnworth et al.

U.S. Patent Application No. 10/201,208, filed July 22, 2002, entitled "Thick Solder Mask for Confining Encapsulant Material Over Selected Locations of a Substrate, Assemblies Including the Solder Mask, and Methods", inventor Grigg et al.

U.S. Patent Application 10/370,755, filed February 20, 2003, entitled "Chip Scale Package Structures and Method of Forming Conductive Bumps Thereon", inventor Warren M. Farnworth

U.S. Patent Application No. 10/608,749, filed June 26, 2003, entitled "Methods for Labeling Semiconductor Device Components", inventor Grigg et al.

U.S. Patent Application No. 10/619,918, filed July 15, 2003, entitled "Stereolithographic Methods for Fabricating Hermetic Semiconductor Device Packages and Semiconductor Devices Including Stereolithographically Fabricated Hermetic Packages", inventor Warren M. Farnworth

U.S. Patent Application No. 10/642,908, filed August 18, 2003, entitled "Solder Masks for Use on Carrier Substrates, Carrier Substrates and Semiconductor Device Assemblies Including Such Solder Masks, and Methods", inventor Tan et al.

U.S. Patent Application No. 10/663,402, filed September 16, 2003, entitled "Processes for Facilitating Removal of Stereolithographically Fabricated Objects from Platens of Stereolithographic Fabrication Equipment, Object Release Elements for Effecting Such Processes, Systems and Fabrication Processes Employing the Object Release Elements, and Objects Which Have Been Fabricated Using the Object Release Elements", inventor Farnworth et al.

U.S. Patent Application No. 10/688,354, filed October 17, 2003, entitled "Thick Solder Mask for Confining Encapsulant Material Over Selected Locations of a Substrate and Assemblies Including the Solder Mask", inventor Grigg et al.

U.S. Patent Application No. 10/690,417, filed October 20, 2003, entitled "Methods of Coating and Singulating Wafers and Chip-Scale Packages Formed Therefrom", inventor Farnworth et al.

Applicant offers to supply any explanation or discussion of the documents which the Examiner feels is necessary or desirable and which is requested.

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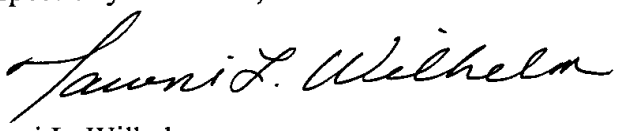
The fee pursuant to 37 C.F.R. § 1.17(p) is enclosed.

Respectfully submitted,



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Group Art Unit	1722
Examiner Name	E. Luk
Attorney Docket Number	3996US (99-0254.00/US)

U.S. PATENT DOCUMENTS

Examiner Initials *	Cite No.[1]	Document Number Number - Kind Code[2] (*if known*)	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		US-6,251,488	06/26/01	Miller et al.	
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		US- 6,326,698	12/04/01	Akram	
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		US- 6,544,821	04/08/03	Akram	
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		US-6,607,689	08/19/03	Farnworth	
		US-6,635,333	10/21/03	Grigg et al.	

FOREIGN PATENT DOCUMENTS

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OTHER PRIOR ART -- NON PATENT LITERATURE DOCUMENTS

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